

**IN THE CLAIMS:**

On page 13, in line 1, cancel "Patent Claims" substitute --**WE CLAIM AS OUR INVENTION:**-- therefor.

Please cancel claims 1-20.

Please add the following new claims 21-40:

1. ~~21.~~ A method for producing a surface mounting optoelectronic component having a base body, an optoelectronic transmitter/receiver that is arranged in a recess of the base body, and an optical device that covers the recess, said method comprising the steps of:

preparing the base body with the optoelectronic transmitter/receiver arranged in the recess;

filling the recess of the prepared base body with a transparent hardenable casting compound;

then placing the optical device onto the as yet uncured casting compound; and

then curing the casting compound.

2. ~~22.~~ The method as claimed in claim ~~21~~<sup>1</sup>, wherein the step of preparing the base body comprises the steps of:

coating a conductor strip with a thermoplast housing while

simultaneously forming the recess of the base body into a top surface of the thermoplast housing, a portion of said conductor strip being situated inside the recess;

mounting the optoelectronic transmitter/receiver on said portion of the conductor strip situated inside the recess; and

filling the recess of the base body with a transparent curable casting compound having thermal characteristics adapted to the thermoplast housing material.

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3. ~~23~~<sup>1</sup> The method as claimed in claim ~~21~~<sup>1</sup>, wherein the recess of the base body is filled with the casting compound to a level such that, during the subsequent placement of the optical device, essentially no casting compound runs over an edge of the recess.

5 4. ~~24~~<sup>3</sup> The method as claimed in claim ~~23~~<sup>3</sup>, wherein the recess is filled with casting compound essentially to the edge of the recess such that, after the recess is filled with casting compound, a fillet develops owing to the surface tension of the casting compound; and wherein the optical device has a shape in a region contacting the casting compound that no casting compound runs over the

10 edge of the recess when the optical device is subsequently placed onto the casting compound.

5. ~~25~~<sup>1</sup> The method as claimed in claim ~~21~~<sup>1</sup>, wherein said optical device is placed from above, without pressure, onto one of the base body or at least one seating element attached to said base body within said recess.

15 6. ~~26~~<sup>1</sup> The method as claimed in claim ~~21~~<sup>1</sup>, wherein the casting compound is cured by the influence of heat.

7. ~~27~~<sup>1</sup> The method as claimed in claim ~~21~~<sup>1</sup>, further comprising the steps of:

20 prior to filling the recess, producing an optical device by one of casting, pressing, or injection processing;

then readying and transporting the optical device as bulk material of optical devices;

then automatically picking a respective optical device from the bulk material; and

25 then automatically positioning the picked optical device over the base body.

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preparing the base body with the optoelectronic transmitter/receiver  
arranged in the recess;

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then at least partially curing at least one of the first casting compound in the recess of the base body and the second casting compound in the mold half;

then casting the optical device onto the base body by joining the base body and the mold half properly positioned, such that second casting compound in the mold half comes into contact with a surface of the first casting compound in the recess of the base body;

then curing at least one of the second and first casting compound; and

then removing the mold half from the base body with the cast-on optical device.

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~~29.~~ The method as claimed in claim ~~28~~, further comprising the steps of:

prior to joining the base body and the mold half, wetting the surface of the first casting compound.



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~~18.~~<sup>10</sup>  
~~36.~~ The method as claimed in claim ~~28~~<sup>10</sup>, wherein the second casting compound is cured at a temperature of approximately 150°C.

~~19.~~<sup>10</sup>  
~~37.~~ The method as claimed in claim ~~28~~<sup>10</sup>, wherein the mold half is removed from the base body at a temperature of approximately 80°C.

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38. A surface mounting optoelectronic component comprising:  
a base body having a thermoplast injection housing and a coated conductor strip secured to the housing, said base body having a recess formed therein with a portion of the conductor strip situated inside the recess;  
an optoelectronic transmitter/receiver arranged in the a recess of the base body and mounted on the portion of the conductor strip situated inside the recess;  
a transparent hardenable casting compound provided in the recess, said casting compound having thermal characteristics adapted to those of the thermoplast housing material; and  
an optical device covering the recess and cast onto the casting compound such that a seating surface of the optical device is in surface-wide contact with the casting compound.
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39. The surface mounting optoelectronic component as claimed in claim 38, wherein the recess comprises a ring channel surrounding the recess.
40. The surface mounting optoelectronic component as claimed in claim 38, wherein the base body comprises a number of seating elements for seating of the optical device, said seating elements being arranged at a margin side relative to the recess.